PREPARED BY	SHARP	SPEC No.	LD-20302A
K. Fogota		FILE No.	
APPROVED BY	MOBILE LIQUID CRYSTAL DISPLAY GROUP	ISSUE	Apr.3.2008
H. Zabuwchi	SHARP CORPORATION	PAGE	Pages 28
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	CARCUELCA ELON	MOBILE LCD I	
	SPECIFICATION		
These parts CUSTOMER'S APPE	DEVICE SPECIFICATION for TFT LCD Module (320 × RGB × 240 dots) Model No. LQ035Q3DW0 have corresponded with the	RoHS dire	ective.
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BY	BY W. K. SHIONO	- In in	
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		quid Crystal Di	isplay Group
	SHARP C	ORPORATION	

RECORDS OF REVISION

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1. Applicable Scope

This specification is applicable to TFT-LCD Module "LQ035Q3DW02".

2. General Description

This module is a color active matrix LCD module incorporating amorphous silicon TFT (<u>Thin Film Transistor</u>). It is composed of a color TFT-LCD panel, driver IC, Input FPC, a back light unit.

Graphics and texts can be displayed on a 320 × RGB × 240 dots panel with about 262k colors by supplying 18bit data signals (6bit × RGB), four timing signals, 3wires 9 / 24bit serial interface signals,

logic (Typ. +3.3V),analog (Typ. +3.3V) supply voltages for TFT-LCD panel driving and supply voltage for back light.

3. Mechanical (Physical) Specifications

Item	Specifications	Unit
Screen size	8.8(3.5" type) diagonal	cm
Active area	70.56 (H) × 52.92 (V)	mm
Divel former	320 (H) × 240 (V)	pixel
Pixel format	1 Pixel = R+G+B dots	-
Pixel pitch	0.2205 (H) × 0.2205(V)	mm
Pixel configuration	R,G,B vertical stripes	-
Display mode	Normally black	-
Unit outline dimensions *	76.9(W) × 63.9 (H) × Max3.5(D)	mm
Mass	Approx.33	g
Surface treatment	Anti glare	-

^{*}The above-mentioned table indicates module sizes without some projections and FPC. For detailed measurements and tolerances, please refer to 17. Outline Dimensions.

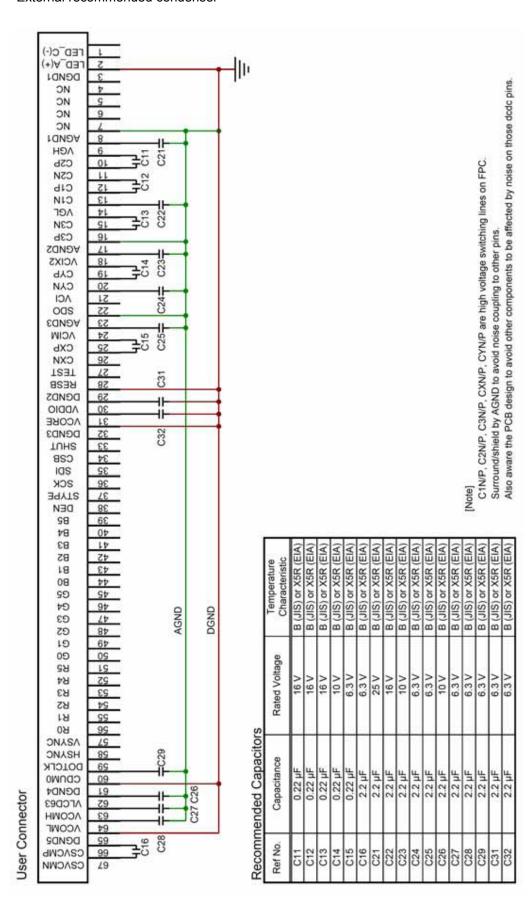
4. Input Terminal Names and Functions

Recommendation CN: [HIROSE] FH26G-67S-0.3SHBW(05)

			_	Description	Domorko
2 LED_A(+) - Power supply for LED (Anode: High voltage) 3 DGND1 - Digital Ground 4 NC - Not connected 5 NC - Not connected 6 NC - Not connected 7 NC - Not connected 8 AGND1 - Analog Ground 9 V _{GH} - Connect to a Stabilizing capacitor Note 3 10 C2P - Connect a Booster capacitor to C2N Note 2 11 C2N - Connect a Booster capacitor to C2P Connect a Booster capacitor to C1N 13 C1N - Connect a Booster capacitor to C1N Onte 3 14 V _{GL} - Connect a Booster capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to GND Note 3 17 AGND2 - Connect a Booster capacitor to CYN	Pin No.	Symbol	I/O	Description (Co. 1)	Remarks
3		- '	-		
4 NC - Not connected 5 NC - Not connected 6 NC - Not connected 7 NC - Not connected 8 AGND1 - Analog Ground 9 V _{GH} - Connect a Stabilizing capacitor Note 3 10 C2P - Connect a Booster capacitor to C2N Note 2 11 C2N - Connect a Booster capacitor to C2P Connect a Booster capacitor to C1N 13 C1N - Connect a Booster capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to GND Note 2 16 C3P - Connect a Booster capacitor to GND Note 2 17 AGND2 - Analog Ground Note 3 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a					
Note			-	-	
Note		NC	-	Not connected	
NC	5	NC	-	Not connected	
Note 3	6	NC	-	Not connected	
9 V _{GH} - Connect to a Stabilizing capacitor Note 3 10 C2P - Connect a Booster capacitor to C2N Note 2 11 C2N - Connect a Booster capacitor to C2P 12 C1P - Connect a Booster capacitor to C1N 13 C1N - Connect a Booster capacitor to C1P 14 V _{GL} - Connect a Stabilizing capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to C3N Note 2 17 AGND2 - Connect a Booster capacitor to C3N Note 3 19 CYP - Connect a Booster capacitor to CYN Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP Note 3 21 V _{C1} - Booster input voltage pin Note 3 22 SDO O Data output pin in	7	NC	-	Not connected	
10	8	AGND1	-	Analog Ground	
11	9	V_{GH}	-	Connect to a Stabilizing capacitor	Note 3
12 C1P - Connect a Booster capacitor to C1N 13 C1N - Connect a Booster capacitor to C1P 14 V _{GL} - Connect a Stabilizing capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to C3N 17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP Note 3 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN </td <td>10</td> <td>C2P</td> <td>-</td> <td>Connect a Booster capacitor to C2N</td> <td>Note 2</td>	10	C2P	-	Connect a Booster capacitor to C2N	Note 2
13 C1N - Connect a Stabilizing capacitor to C1P 14 V _{GL} - Connect a Stabilizing capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to C3N 17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP Digital Ground 29	11	C2N	-	Connect a Booster capacitor to C2P	
14 V _{GL} - Connect a Stabilizing capacitor to GND Note 3 15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to C3N 17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP Note 3 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB	12	C1P	-	Connect a Booster capacitor to C1N	
15 C3N - Connect a Booster capacitor to C3P Note 2 16 C3P - Connect a Booster capacitor to C3N 17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground	13	C1N	-	Connect a Booster capacitor to C1P	
16 C3P - Connect a Booster capacitor to C3N 17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 <td< td=""><td>14</td><td>V_{GL}</td><td>-</td><td>Connect a Stabilizing capacitor to GND</td><td>Note 3</td></td<>	14	V_{GL}	-	Connect a Stabilizing capacitor to GND	Note 3
17 AGND2 - Analog Ground 18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	15	C3N	-	Connect a Booster capacitor to C3P	Note 2
18 V _{CIX2} - Connect a Stabilizing capacitor to GND Note 3 19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	16	C3P	-	Connect a Booster capacitor to C3N	
19 CYP - Connect a Booster capacitor to CYN Note 2 20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	17	AGND2	-	Analog Ground	
20 CYN - Connect a Booster capacitor to CYP 21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	18	V_{CIX2}	-	Connect a Stabilizing capacitor to GND	Note 3
21 V _{CI} - Booster input voltage pin Note 3 22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	19	CYP	-	Connect a Booster capacitor to CYN	Note 2
22 SDO O Data output pin in serial mode 23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	20	CYN	-	Connect a Booster capacitor to CYP	
23 AGND3 - Analog Ground 24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	21	V_{CI}	-	Booster input voltage pin	Note 3
24 V _{CIM} - Connect a Stabilizing capacitor to GND Note 3 25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	22	SDO	0	Data output pin in serial mode	
25 CXP - Connect a Booster capacitor to CXN Note 2 26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	23	AGND3	-	Analog Ground	
26 CXN - Connect a Booster capacitor to CXP 27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	24	V_{CIM}	-	Connect a Stabilizing capacitor to GND	Note 3
27 ID O ID Note 1 28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	25	CXP	-	Connect a Booster capacitor to CXN	Note 2
28 RESB I System reset 29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	26	CXN	-	Connect a Booster capacitor to CXP	
29 DGND2 - Digital Ground 30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	27	ID	0	ID	Note 1
30 V _{DDIO} - Voltage input pin for logic I/O 31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	28	RESB	I	System reset	
31 V _{CORE} - Connect a Stabilizing capacitor to GND Note 3	29	DGND2	-	Digital Ground	
	30	V_{DDIO}	-	Voltage input pin for logic I/O	
32 DGND3 - Digital Ground	31	V_{CORE}	-	Connect a Stabilizing capacitor to GND	Note 3
	32	DGND3	-	Digital Ground	
33 SHUT I Sleep mode control	33	SHUT	I	Sleep mode control	
34 CSB I Chip select pin of serial interface	34	CSB	I	Chip select pin of serial interface	
35 SDI I Data input pin of serial interface	35	SDI	I	Data input pin of serial interface	
36 SCK I Clock input pin of serial interface	36	SCK	I	Clock input pin of serial interface	
37 STYPE I 9bit / 24bit select pin of serial interface 'L'=24bit / 'H'=	37	STYPE	I	9bit / 24bit select pin of serial interface	'L'=24bit / 'H'=9bit
38 DEN I Display enable signal	38	DEN	I	Display enable signal	
39 B5 I BLUE data signal(MSB)	39	B5	I	BLUE data signal(MSB)	
40 B4 I BLUE data signal	40	B4	I	BLUE data signal	
41 B3 I BLUE data signal	41	В3	I	BLUE data signal	

				LD 20002i
Pin No.	Symbol	I/O	Description	Remarks
42	B2	I	BLUE data signal	
43	B1	I	BLUE data signal	
44	В0	I	BLUE data signal(LSB)	
45	G5	I	GREEN data signal(MSB)	
46	G4	I	GREEN data signal	
47	G3	I	GREEN data signal	
48	G2	I	GREEN data signal	
49	G1	I	GREEN data signal	
50	G0	I	GREEN data signal(LSB)	
51	R5	I	RED data signal(MSB)	
52	R4	I	RED data signal	
53	R3	I	RED data signal	
54	R2	I	RED data signal	
55	R1	I	RED data signal	
56	R0	I	RED data signal(LSB)	
57	VSYNC	I	Frame synchronization signal	
58	HSYNC	I	Line synchronization signal	
59	DOTCLK	I	Dot-clock signal	
60	CDUM0	-	Connect a Charge sharing capacitor to GND	Note 4
61	DGND4	-	Digital Ground	
62	V _{LCD63}	-	Connect a Stabilizing capacitor to GND	Note 3
63	V _{COMH}	-	Connect a Stabilizing capacitor to GND	
64	V_{COML}	-	Connect a Stabilizing capacitor to GND	
65	DGND5	-	Digital Ground	
66	CSVCMP	-	Connect a Charge sharing capacitor to CSVCMN	Note 4
67	CSVCMN	-	Connect a Charge sharing capacitor to CSVCMP	

- Note 1) ID pin connects with VDDIO on an FPC.
- Note 2) Booster Capacitors.
- Note 3) Stabilization and charge sharing Capacitors.
- Note 4) Charge sharing Capacitors



5. Absolute Maximum Ratings

Item	Symbol	Conditions	Rated value	Unit	Remarks
Input voltage	VI	Ta = 25°C	-0.3 ~ V _{DDIO} +0.3	V	Note 1
Logic I/O power supply voltage	V_{DDIO}	Ta = 25°C	-0.3 ~ +4.0	V	
Analog power supply voltage	V _{CI}	Ta = 25°C	AGND-0.3 ~ +5.0	V	
Temperature for storage	Tstg	-	-25 ~ +70	°C	Note 2
Temperature for operation	Торр	-	-10 ~ +70	°C	Note 3
LED input electric current	I _{LED}	Ta = 25°C	35	mA	
LED electricity consumption	P _{LED}	Ta = 25°C	123	mW	Note 4

Note 1) RESB, SHUT, CSB, SDI, SCK, STYPE, DEN, B5~B0, G5~G0, R5~R0, VSYNC, HSYNC, DOTCLK

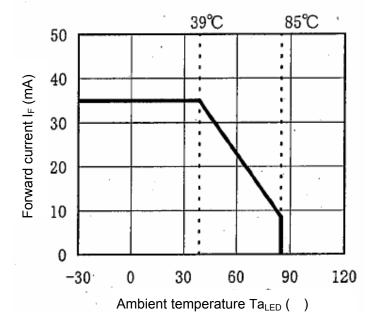
Note 2) Humidity: 95%RH Max. (Ta 40°C)

Maximum bulb temperature under 39°C (Ta>40°C) See to it that no dew will be condensed.

Note 3) Panel surface temperature prescribes.

Note 4) Power consumption of one LED (Ta_{LED} = 25°C). (use 7 pieces LED)

Ambient temperature and the maximum input are fulfilling the following operating conditions.



Ambient temperature of LED and the maximum input

6. Electrical Characteristics

6-1. TFT LCD Panel Driving

Ta = 25°C

Item		Symbol	Min.	Тур.	Max.	Unit	Remarks
Logic I/O	DC voltage	V_{DDIO}	+3.0	+3.3	+3.6	V	
power supply	DC Current	I _{VDDIO}	-	0.55	0.95	mA	Note 1
Analog	DC voltage	V _{CI}	+3.0	+3.3	+3.6	V	
power supply	DC Current	I _{VCI}	-	9.5	12	mA	Note 1
Permis	sive input	V _{RFVDDIO}	-	-	100	mVp-p	Note 2
Ripple	voltage	V _{RFVCI}	-	-	100	mVp-p	Note 2
Logic	High	V _{IH}	0.8 V _{DDIO}	-	V_{DDIO}	V	Note 3
Input Voltage	Low	V _{IL}	0	-	0.2 V _{DDIO}	V	Note 3
Logic inp	out Current	I _{IH} / I _{IL}	-1	-	1	μΑ	Note 3

Note 1) $V_{DDIO} = V_{CI} = +3.3V$

Current situation for I_{VDDIO}: Black & White checker flag pattern

Current situation for I_{CI} : All white pattern

Note 2) $V_{DDIO} = V_{CI} = +3.3V$

Note 3) RESB, SHUT, CSB, SDI, SCK, STYPE, DEN, B5~B0, G5~G0, R5~R0, VSYNC, HSYNC, DOTCLK

$$V_{DDIO}$$
 / V_{CI} ON (hold RESB = "L")

 \downarrow

Wait min. 80us

 \downarrow

Hard Reset (RESB "L" \rightarrow "H")

 \downarrow

Display Data Start (VSYNC, HSYNC, DOTCLK)

 \downarrow

Enter the Sleep Mode

Reg. #	Register	Data	Remark
R11h	Power control (8)	0001 h	Note 2

Register setting

Reg.#	Register	Data (Gamma 2.2)	Remark
R01 h	Driver output control	0xEF h	Note 1
R02 h	LCD drive AC control	0300h	
R03 h	Power control (1)	0A0E h	
R0B h	Frame cycle control	D000 h	
R0C h	Power control (2)	0005 h	
R0D h	Power control (3)	000F h	
R0E h	Power control (4)	2E00 h	
R12 h	Input data format	006x h	Note 3
R16 h	Horizontal Porch	9F86 h	Note 4
R17 h	Vertical Porch	0002 h	Note 5
R1E h	Power control (5)	0000 h	
R28 h	Power control (6)	0006 h	
R2A h	Power control (7)	0187 h	
R30 h	Gamma control (1)	0006 h	
R31 h	Gamma control (2)	0207 h	
R32 h	Gamma control (3)	0000 h	
R33 h	Gamma control (4)	0107 h	
R34 h	Gamma control (5)	0707 h	
R35 h	Gamma control (6)	0005 h	
R36 h	Gamma control (7)	0107 h	
R37 h	Gamma control (8)	0707 h	
R3A h	Gamma control (9)	1F00 h	
R3B h	Gamma control (10)	0000 h	

Exit the Sleep Mode

Reg. #	Register	Data	Remark
R11h	Power control (8)	0000 h	

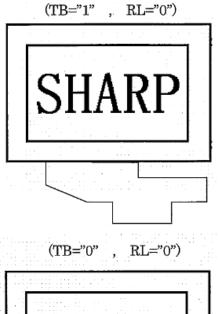
↓
Wait 10 frames time
↓
Display On

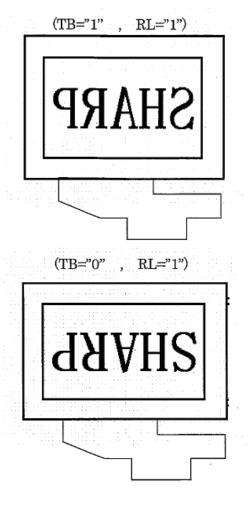
Note 1)

Driver Output Control (R01h)(POR=0xEFh)

R/W	DC	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	0	0	0	0	1	0	TB	RL	1	1	1	0	1	1	1	1
PC)R	0	0	0	0	1	0	х	х	1	1	1	0	1	1	1	1

Vertical and Horizontal inversion function(TB , RL)







Note 2)

mode Control (R11h)(POR=0x0x h)

R/W	DC	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	0	0	0	0	0	0	0	CM	0	0	0	0	0	0	0	SHUT
PC)R	0	0	0	0	0	0	0	Х	0	0	0	0	0	0	0	Х

CM : CM = "0", 262K-color mode. CM = "1", 8 color mode.

SHUT: SHUT ="0", normal mode. SHUT ="1", sleep mode.

Note 3)

mode Control (R12h)(POR=006x h)

R/W	DC	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	0	0	0	0	0	0	0	0	0	IF1	IF0	CM1	IFS1	IFS0	0	0
PC)R	0	0	0	0	0	0	0	0	0	1	1	0	0	Х	0	0

R12h	DEN mode	HV SYNC mode
0060h	Yes	No
0064h	No	Yes

In the case of a DEN mode, more than Vertical Porch = 2 and Horizontal Porch = 4.

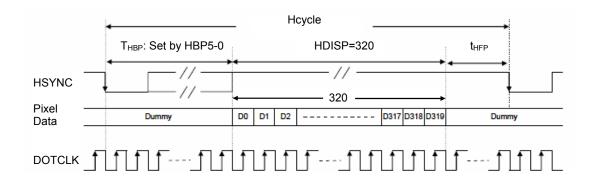
Note 4)

Horizontal Porch(R16h)(POR=9F86h)

R/W	DC	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
W	1	1	0	0	1	1	1	1	1	1	0	HBP5	HBP4	HBP3	HBP2	HBP1	HBP0
PC	R	1	0	0	1	1	1	1	1	1	0	0	0	0	1	1	0

HBP5-0: Set the delay period from falling edge of HSYNC to first valid line.

			ta noming ougo or more to more tame					
HBP4	HBP3	HBP2	HBP1	HBP0	No. of clock cycle of DOTCLK			
0	0	0	0	0	2			
0	0	0	0	1	3			
0	0	0	1	0	4			
0	0	0	1	1	5			
0	0	1	0	0	6			
					:			
	:	:			Step = 1			
					:			
1	1	1	1	0	64			
1	1	1	1	1	65			
	0 0 0 0	HBP4 HBP3 0 0 0 0 0 0 0 0 0 0 0 0 0 0	HBP4 HBP3 HBP2 0 0 0 0 0 0 0 0 0 0 0 0 0 1 0 1 1 1 1 1	HBP4 HBP3 HBP2 HBP1 0 0 0 0 0 0 0 0 0 0 0 1 0 0 1 0 0 0 1 0 0 0 1 0 0 0 1 0	HBP4 HBP3 HBP2 HBP1 HBP0 0 0 0 0 0 0 0 0 0 1 0 0 0 1 0 0 0 1 1 1 0 0 1 0 0 0 0 1 0 0			



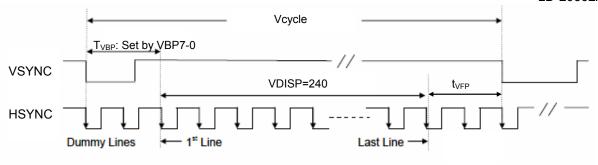
Note 5)

Vertical Porch(R17h)(POR=0002h)

	R/W	DC	IB15	IB14	IB13	IB12	IB11	IB10	IB9	IB8	IB7	IB6	IB5	IB4	IB3	IB2	IB1	IB0
ſ	W	1	0	0	0	0	0	0	0	0	VBP7	VBP6	VBP5	VBP4	VBP3	VBP2	VBP1	VBP0
I	PC	R	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0

VBP8-0: Set the delay period from falling edge of VSYNC to first valid line.

						<u> </u>		
VBP7	VBP6	VBP5	VBP4	VBP3	VBP2	VBP1	VBP0	No. of clock cycle of HSYNC
0	0	0	0	0	0	0	0	0
0	0	0	0	0	0	0	1	1
0	0	0	0	0	0	1	0	2
								:
				:				Step = 1
			:	:				:
1	1	1	0	1	1	1	1	239
1	1	1	1	0	0	0	0	240
1	1	1	1	*	*	*	*	Reserved



6-3. Power down sequence

Write White Data (RGB Data: All "H" level)

↓
Wait min. 1 frame time

↓
Enter the Sleep Mode

Reg.#	Register	Data	Remark
R11h	Power control (8)	0001 h	

Wait min. 2 frames time

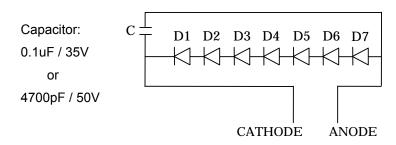
Display Data Stop (VSYNC, HSYNC, DOTCLK) $\downarrow $V_{DDIO} \, / \, V_{CI} \, OFF \label{eq:control}$

6-3. Back light driving

The back light system has 7 LEDs

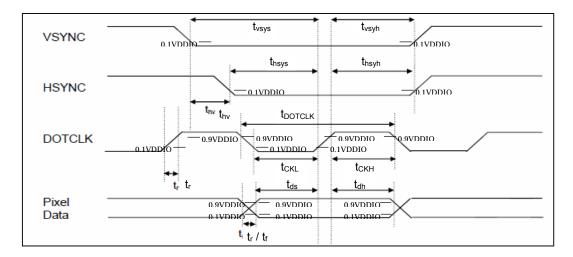
Used LED: NSSW0061[NICHIA] [Luminance: A18 ~ A22, Chromaticity:a62,a67,bj2,bj7]									
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remark			
Rated Voltage	V_{BL}	-	22.4	24.5	V				
Rated Current	ΙL	-	20	-	mA	Ta=25°C			
Power consumption	W∟	-	448	-	mW				

[LED-FPC circuit]



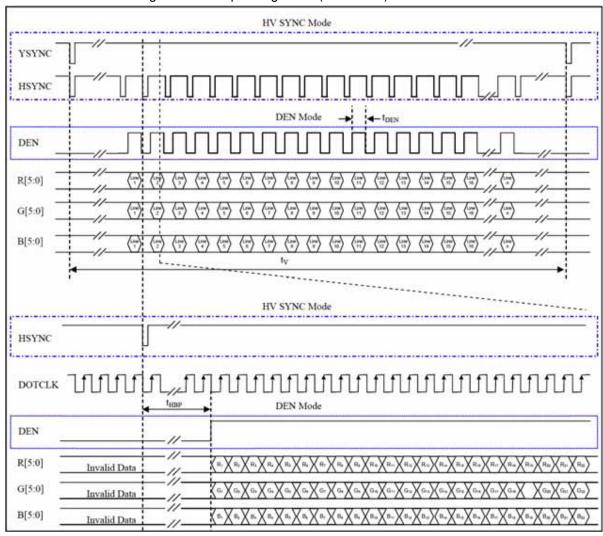
7. Timing characteristics of input signals

7-1. Pixel Clock Timing



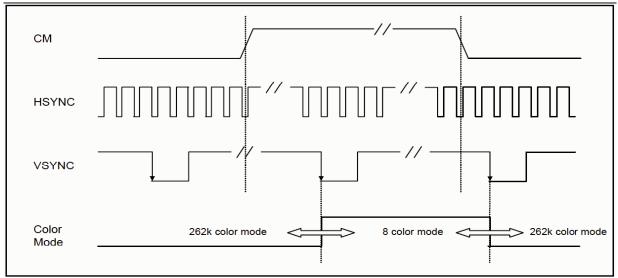
Ch	aracteristics	Symbol	Min	Тур	Max	Unit
DOTCLK	Frequency	f _{DOTCLK}	-	5.0	8.0	MHz
	Period	t _{DOTCLK}	125	200	-	nSec
	High Period	t _{CKH}	16	-	-	nSec
	Low Period	t _{CKL}	16	-	-	nSec
Data	Setup Time	t _{ds}	10	-	-	nSec
	Hold Time	t _{dh}	10	-	-	nSec
Vsync	Setup Time	t _{vsys}	5	-	-	nSec
	Hold Time	t _{vsyh}	5	-	-	nSec
Hsync	Setup Time	t _{hsys}	5	-	-	nSec
	Hold Time	t _{hsyh}	5	-	-	nSec
Phase differe	ence of Sync signal	t _{hv}	0	-	320	t _{DOTCLK}
Falling edge						
Reset Pulse	Width	t _{RES}	2.5	-	-	nSec
Rise / Fall Tir	me	t _r /t _f	5	-	25	nSec

7-2. Data Transaction Timing in Normal Operating Mode (262k color)

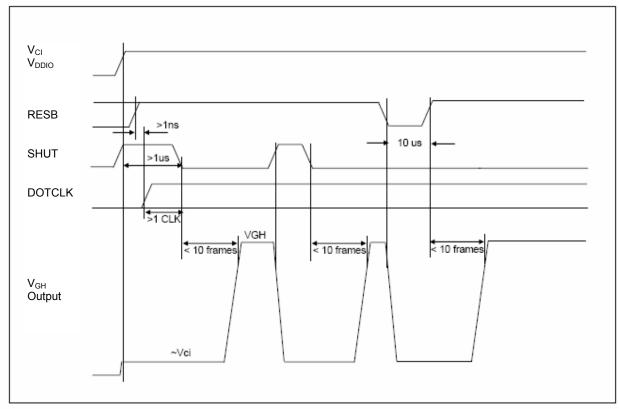


	Characteristics	Symbol	HV SYNC	DEN	Unit
			MODE	MODE	
D	OTCLK Frequency	1/t _{DOTCLK}	5	5	MHz
HSYNC	Period	t _H	336	336	t _{DOTCLK}
	Horizontal Display Area	t _{data}	320	320	t _{DOTCLK}
	Horizontal Back Porch	t _{HBP}	8	-	t _{DOTCLK}
	Horizontal Front Porch	t _{HFP}	8	-	t _{DOTCLK}
	Data Enable Period	t _{DEN}	-	320	t _{DOTCLK}
VSYNC	Period	t _V	244	244	t _H
	Vertical Display Area	t _{AL}	240	240	t _H
	Vertical Back Porch	t _{VBP}	2	-	t _H
	Vertical Front Porch	t _{VFP}	2	-	t _H

7-3. Synchronization Signals Timing in Power Save Mode (8 color)



7-4. V_{GH} Output against SHUT & RESB



VGH Output against SHUT & RESB

Note1: The minimum cycle time of SHUT is 10 + 2 frames.

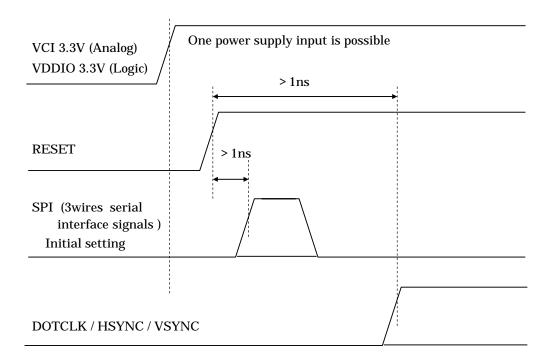
Note2: DOTCLK must be provided for boosting of V_{GH}. The above timing diagram assumed voltages and DOTCLK are

continuous supplied after power on.

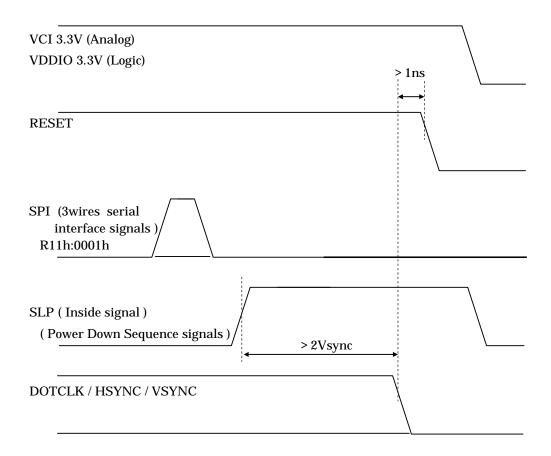
Note3: V_{GH} will be forced to V_{CI} at the low stage of RESB.

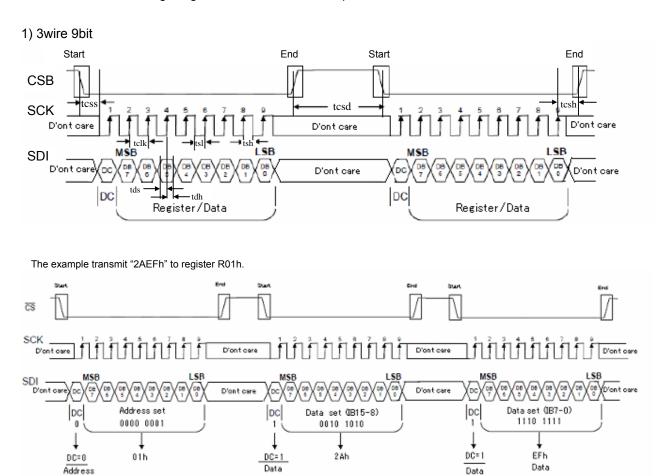
Note4: The minimum pulse width of RESET is 10us.

7-5. Power Up Sequence



7-6. Power Down Sequence





2) 3wire 24bit

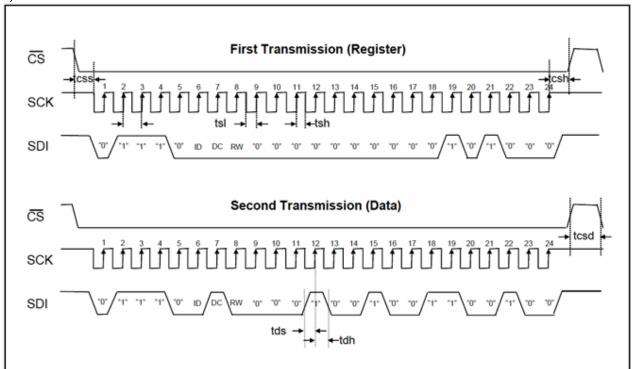
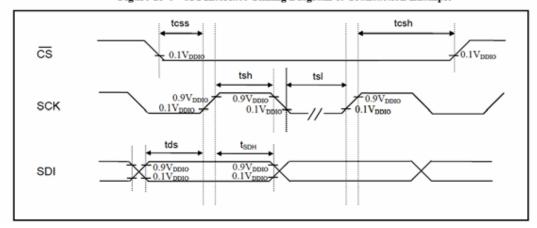
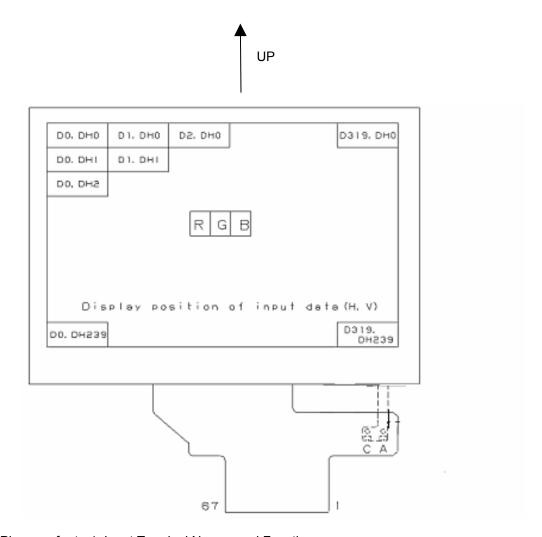


Figure 15-6 - SPI Interface Timing Diagram & Transaction Example



Charac	cteristics	記号	Min	Тур	Max	単 位
Serial Clock	Frequency	fclk	ı	ı	20	MHz
	Cycle Time	tclk	50	-	-	ns
	Low Width	tsl	25	-	-	ns
	High Width	tsh	25	-	-	ns
Chip Select	Setup Time	tcss	0	-	-	ns
	Hold time	tcsh	10	-	-	ns
	High Delay Time	tcsd	20	-	-	ns
Data	Setup Time	tds	5	-	-	ns
	Hold Time	tdh	10	-	-	ns



Please refer to 4. Input Terminal Names and Functions

Please refer to 17. Outline Dimensions.

8. Input Signals, Basic Display Colors and Gray Scale of Each Color

0. 111		ls, Basic Display Colors and Gray Scale of Each Color Date signal																		
	Colors &			ı	ı									ı			1	ı		
	Gray	Gray	R0	R1	R2	R3	R4	R5	G0	G1	G2	G3	G4	G5	B0	B1	B2	В3	B4	B5
	Scale	Scale	LSB MSB				LSB MSB				MSB	LSB MSB								
Basic Color	Black	-	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue	-	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1
	Green	-	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0
	Cyan	-	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1
	Red	-	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	Magenta	-	1	1	1	1	1	1	0	0	0	0	0	0	1	1	1	1	1	1
	Yellow	-	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0
	White	-	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Gray Scale of Red	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	仓	GS1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Darker	GS2	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	仓	V	\downarrow					V					↓							
le of	Û	→	\downarrow				V				ψ									
Red	Brighter	GS61	1	0	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	Û	GS62	0	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	Red	GS63	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
G	仓	GS1	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0
ray	Darker	GS2	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0
Scal	仓	→	V					↓					V							
Gray Scale of Gre	Û	→	V				V				↓									
Gre	Brighter	GS61	0	0	0	0	0	0	1	0	1	1	1	1	0	0	0	0	0	0
en	Ŷ	GS62	0	0	0	0	0	0	0	1	1	1	1	1	0	0	0	0	0	0
	Green	GS63	0	0	0	0	0	0	1	1	1	1	1	1	0	0	0	0	0	0
Gray Scale of Blue	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Û	GS1	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0
	Darker	GS2	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0
	仓	\	↓				→				↓									
	Ŷ	V	\downarrow				\downarrow				\downarrow									
	Brighter	GS61	0					0	0	0	0	0	0	1	0	1	1	1	1	
	Ţ.	GS62	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1
	Blue	GS63	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1
				l	l					L		L	L	L.,	L.,	L	h lo	Щ.	<u> </u>	

0: Low level voltage, 1: High level voltage

Each basic color can be displayed in 64 gray scales from 6 bit data signals.

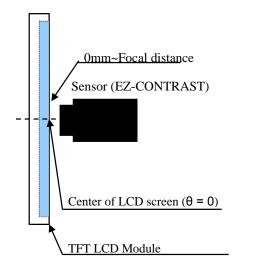
According to the combination of 18 bit data signals, the 262k color display can be achieved on the screen.

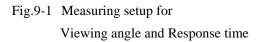
9. Optical Characteristics

$T_2 = 25$:°C \/	= +3.3V	V - +3	2 21/
1a = 25) U. Vinnic	1 = +3.3V.	Vc1 = +3	3.3V

						-, - DDIO		<u>.</u>	
Parar	meter	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	
Viewing	Horizontal	θ21		ı	80	ı	deg.		
angle		θ22	CR 10	ı	80	ı	deg.	F N1-1-4-4 3	
range (Wide View)	Vertical	θ11		-	80	-	deg.	【Note1,4】	
(*******)	Vertical	θ12		-	80	-	deg.		
Contrast ratio		CR	Optimum viewing angle	100	500	1		【Note2,4】	
Response	Rise	Tr		-	15	30	ms		
Time Decay		Td		ı	15	30	ms	【Note3,4】	
Chroma	aticity of	х	0.00	0.26	0.31	0.36	-		
White		у	θ=0°	0.29	0.34	0.39	-	【Note4】	
Luminano	ance of white XL1			350	450	_	cd/m²	ILED=20mA	
Luillilaile	e oi wille	ALI		330	730	_	Cu/III²	【Note4】	

^{*} The optical characteristics measurements are operated under a stable luminescence (ILED = 20mA) and a dark condition. (Refer to Fig.9-1 and Fig.9-2)





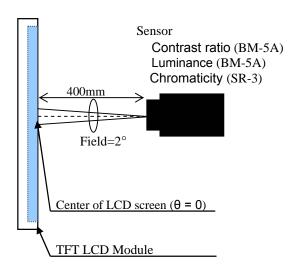
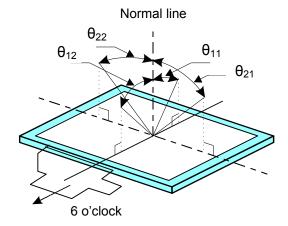


Fig.9-2 Measuring setup for
Luminance, Chromaticity and Contrast ratio

[Note 1] Definitions of viewing angle range

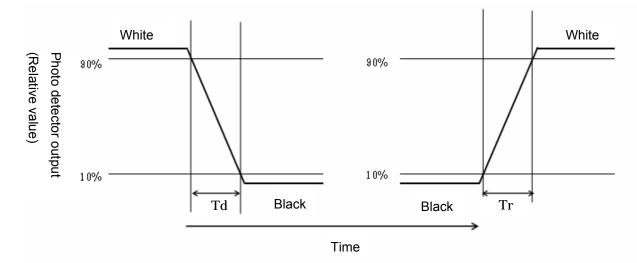


[Note 2] Definition of contrast ratio

The contrast ratio is defined as the following $Contrast\ ratio\ (CR) = \frac{Luminance\ (brightness)\ with\ all\ pixels\ white}{Luminance\ (brightness)\ with\ all\ pixels\ black}$

[Note 3] Definition of response time

The response time is defined as the following figure and shall be measured by switching the input signal for "Black" and "White"



[Note 4] This shall be measured at center of the screen.

10 Handling of modules

- 10-1. Inserting the FPC into its connector and pulling it out
- 1) Be sure to turn off the power supply and the signals when inserting or disconnecting the cable.
- 2) Please insert for too much stress not to join FPC in the case of insertion of FPC.

10-2. About handling of FPC

- 1) The bending radius of the FPC should be more than 1.4mm, and it should be bent evenly.
- 2) Do not dangle the LCD module by holding the FPC, or do not give any stress to it.

10-3. Mounting of the module

- 1) The module should be held on to the plain surface. Do not give any warping or twisting stress to the module.
- 2) Please consider that GND can ground a modular metal portion etc. so that static electricity is not charged to a module.

10-4. Cautions in assembly / Handling pre cautions

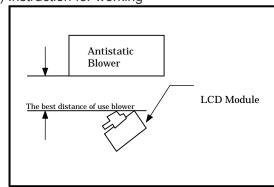
As the polarizer can be easily scratched, be most careful in handling it.

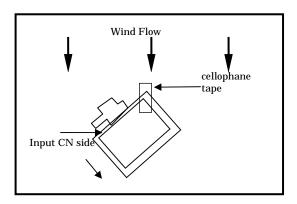
1) Work environments in assembly.

Since removing laminator may causes electrostatic charge that tends to attract dust, the following work environment would be desired.

- a) Floor: Conductive treatment having $1M\Omega$ resistance onto floor's tile
- b) The room free from dust coming from outdoor environment, and put an adhesive mat at entrances.
- c) Humidity from 50% to 70% and temperature from 15°C to 27°C are desirable.
- Worker should ware conductive shoes, conductive fatigue, conductive glove and earth wrist band.

2) Instruction for working





- a) Wind direction of an antistatic blower should slightly downward to properly blow the module.

 The distance between the blower and the module should
 be the best distance of use blower. Also, pay attention to the direction of the module.
- b) To prevent polarizer from scratching, adhesive tape (cellophane tape) should be stuck at the part of laminator sheet, which is closed to blower. [See the above]
- c) Pull slowly adhesive tape to peel the laminator off, with spending more than 5 second.
- d) The module without laminator should be moved to the next process to prevent adhesion of dust.

- 3) How the remove dust on the polarizer
 - a) Blow out dust by the use of an N2 blower with antistatic measures taken. Use of an ionized air Gun is recommendable.
 - b) When the panel surface is soiled, wipe it with soft cloth.
- 4) In the case of the module's metal part (shield case) is stained, wipe it with a piece of dry, soft cloth.

 If rather difficult, give a breath on the metal part to clean better.
- 5) If water dropped, etc. remains stuck on the polarizer for a long time, it is apt to get discolored or cause stains. Wipe it immediately.
- 6) As a glass substrate is used for the TFT-LCD panel, if it is dropped on the floor or hit by something hard, it may be broken or chipped off.
- 7) Since CMOS LSI is used in this module, take care of static electricity and take the human earth into consideration when handling.

10-5. Others

- 1) Regarding storage of LCD modules, avoid storing them at direct sunlight-situation.
- 2) If stored at temperatures below the rated values, the inner liquid crystal may freeze, causing cell destruction. At temperatures exceeding the rated values for storage, the liquid crystal may become isotropic liquid, making it no longer possible to come back to its original state in some cases.
- 3) If the LCD is broken, do not drink liquid crystal in the mouth. If the liquid crystal adheres to a hand or foot or to clothes, immediately cleanse it with soap.
- 4) If a water drop or dust adheres to the polarizer, it is apt to cause deterioration. Wipe it immediately.
- 5) Be sure to observe other caution items for ordinary electronic parts and components.

11. Reliability test items

	Teliability test items								
No.	Test item	Conditions							
1	High temperature storage test	Leaves the module at Ta=+70°C for 240h							
2	Low temperature storage test	Leaves the module at Ta=-25°C for 240h							
3	High temperature & high humidity operation test	Operates the module at Ta=+40°C; 95%RH for 240h (No condensation)							
4	High temperature operation test	Operates the module with +70°C at panel surface for 240h							
5	Low temperature operation test	Operates the module at Ta=10°C for 240h							
6	Vibration test (non- operating)	Frequency range: 10 to 55Hz Stroke: 1.5mm Sweep time: 1minutes Test period: 2 hours (40 minutes for each direction of X,Y,Z)							
7	Shock test	Impact value: 980m/s², Action time 6ms Direction: ±X, ±Y, ±Z, Time: Third for each direction.							
8	Thermal shock test	Ta=-25°C to 70°C /10 cycles (30 min) (30min)							

[Note] Ta = Ambient temperature, Tp = Panel temperature

[Check items]

In the standard condition, there shall be no practical problems that may affect the display function.

12. Display Grade

The standard regarding the grade of color LCD displaying modules should be based on the delivery inspection standard.

13. Delivery Form

1) Carton piling-up: Max 8 rows

2) Environments

Temperature: 0 ~ 40°C

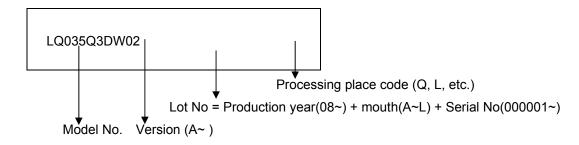
Humidity: 65% RH or less (at 40°C)

There should be no dew condensation even at a low temperature and high humidity.

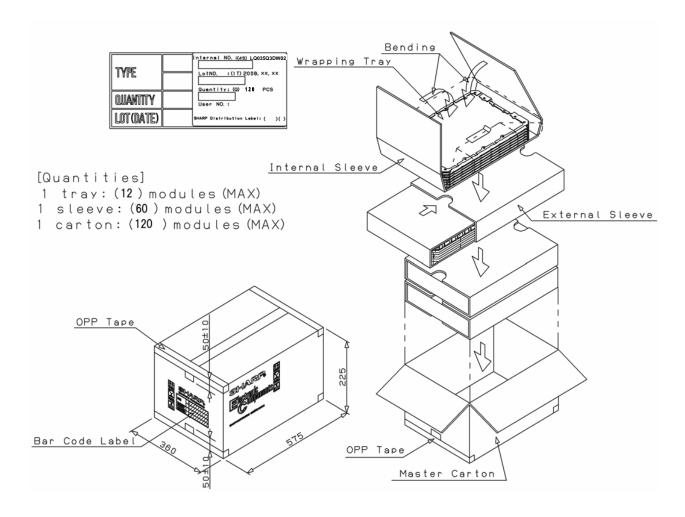
3) Packing form: 15. LCD module packing carton

14. Lot No. marking

The lot No. will be indicated on individual inkjet. The location is as shown



15. LCD module packing carton



16. Others

- 1 Disassembling the module can cause permanent damage and you should be strictly avoided.
- 2 Please be careful that you don't keep the screen displayed fixed pattern image for a long time, since retention may occur.
- 3 If any problem arises regarding the items mentioned in this specification sheet or otherwise, it should be discussed and settled mutually in a good faith for remedy and/or improvement.

17. Outline Dimensions

